



University of Pittsburgh

CS 1541 Introduction

Technology Constraints

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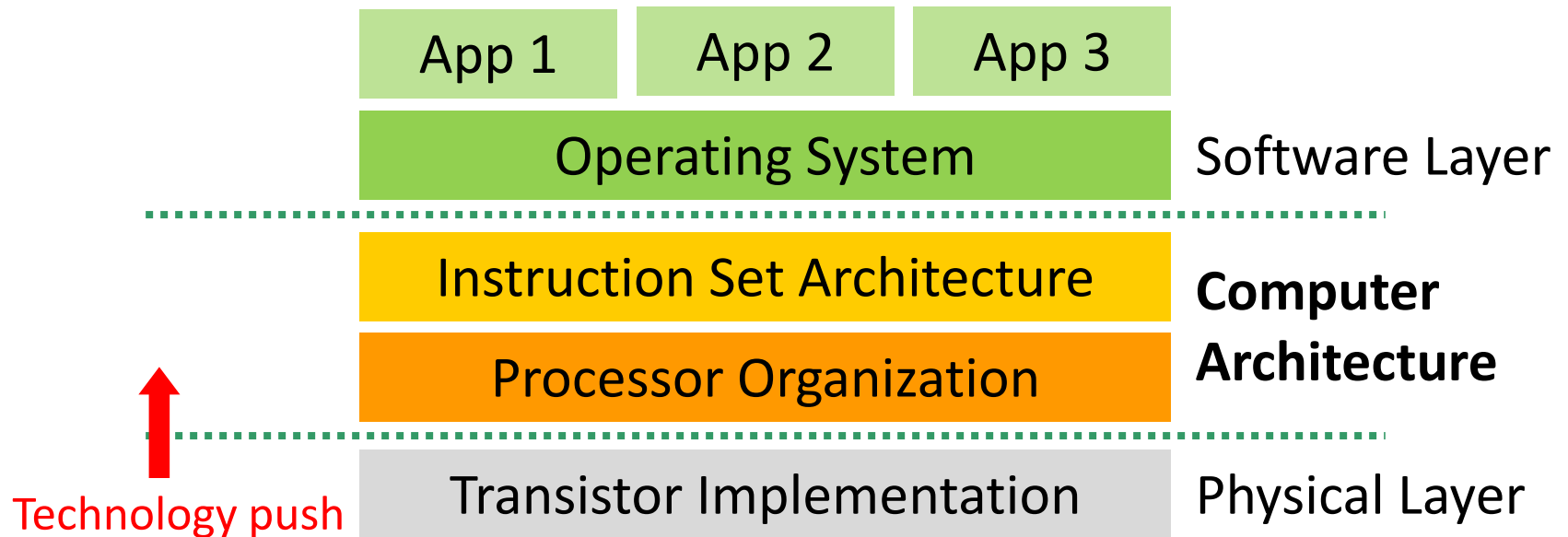
Technology Constraints





Technology Constraints

- Constraints in technology push architecture too



- *Power Wall*: Thermal Design Power (TDP) constraint
- *Memory Wall*: Constraint in bandwidth to memory
- *Variability*: Limits in the precision of manufacturing technology

- Processor must be designed to meet all constraints



Power Wall

- $\text{Power}_{\text{CPU}} = \text{Power}_{\text{dynamic}} + \text{Power}_{\text{leakage}}$
 $\text{Power}_{\text{dynamic}} \propto A * N * CFV^2$
 $\text{Power}_{\text{leakage}} \propto f(N, V, V_{\text{th}}) \propto N * V * e^{-V_{\text{th}}}$
 - Leakage power is also called *static power*
 - This total CPU power cannot exceed TDP

- Moore's Law transistor scaling means two things:
 - $N = \text{Number of transistors} (\propto 1/\text{transistor size}^2) \uparrow \uparrow$
 - $C = \text{Capacitance} (\propto \text{transistor size}) \downarrow$
 - Reductions in C does not compensate for increases in N

- Architects must use tricks to keep power in check
 - To keep packing more transistors to increase performance



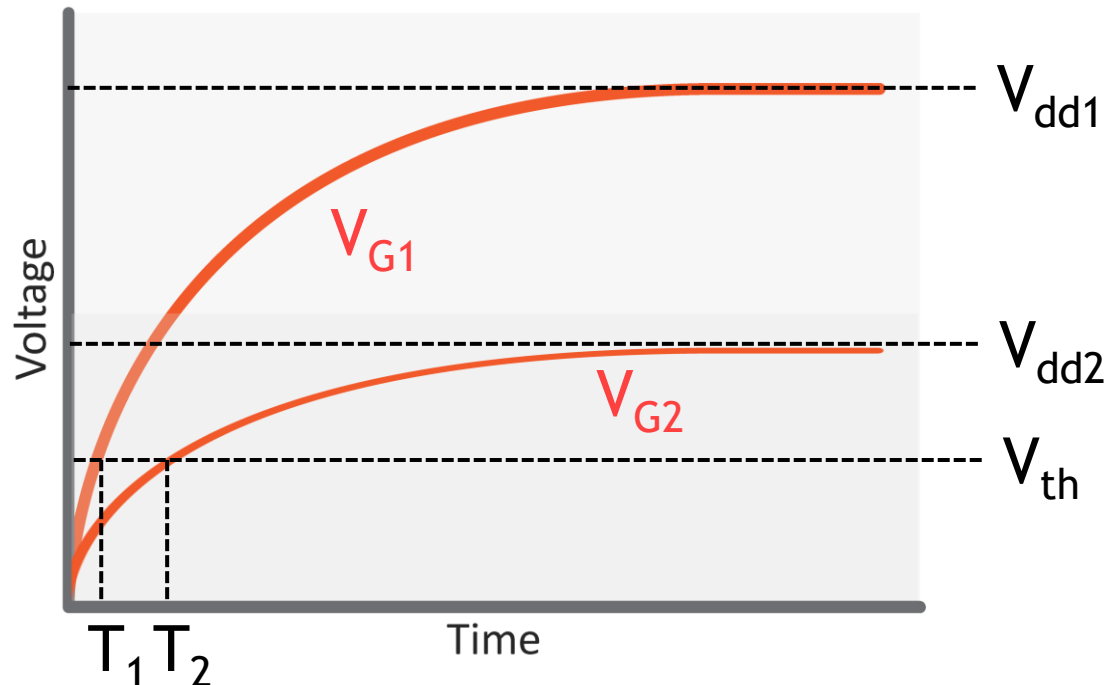
1. Reducing Dynamic Power

- **Power_{dynamic}** ($\propto A * N * CFV^2$) + **Power_{leakage}** ($\propto N * V * e^{-V_{th}}$)
- Reducing A (Activity): *Clock gating*
 - Disables the clock signal to unused parts of the chip (idle cores)
 - Wake-up is instantaneous (the moment clock signal goes in)
- Reducing F (Frequency) and V (Supply Voltage)
 - When F is reduced, V can also be reduced
(The RC curve and water pressure, remember?)
 - *Dynamic Voltage Frequency Scaling (DVFS)* done on multi-cores
 - Slow down low-priority cores, speed up high-priority cores



DVFS and Transistor Speed

■ RC Charging Curve of V_G



- Delay (T) increases with supply voltage (V_{dd}) decrease
→ Frequency ($1/T$) decreases with V_{dd} decrease



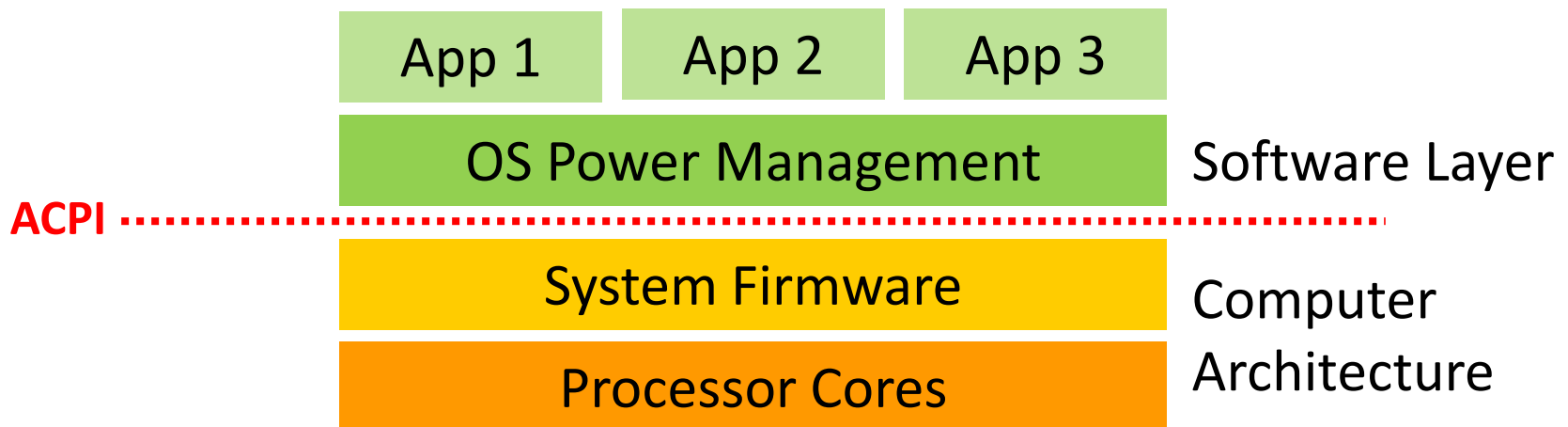
2. Reducing Leakage Power

- $\text{Power}_{\text{dynamic}} (\propto A * N * CFV^2) + \text{Power}_{\text{leakage}} (\propto N * V * e^{-V_{th}})$
- Reducing N (Transistor Number): *Power gating*
 - Disables power to unused parts of the chip (unused cores)
 - Eliminates dynamic power *and* leakage power to those parts
 - Drawback: wake-up takes a much longer time than clock gating
 - Delay for supply voltage to stabilize
 - Delay to backup and restore CPU state to/from memory
- Reducing V (Supply Voltage): *DVFS* also helps here
 - Only the voltage scaling part, not the frequency scaling



OS Manages Power

- Who decides which cores to clock gate and power gate?
- Who decides how to apply DVFS to the cores?
- *ACPI (Advanced Configuration and Power Interface)*
 - OS performs power management using this interface
 - OS knows best which threads to prioritize for best user experience
 - Open standard interface to system firmware
 - Firmware sends signals to processor cores to control them





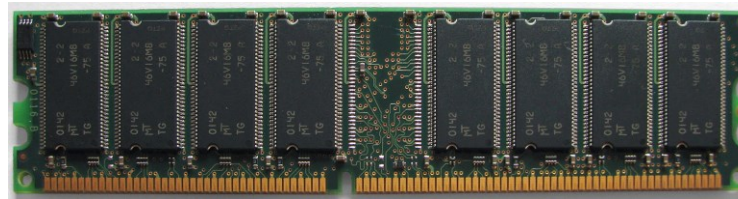
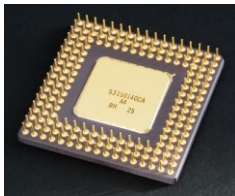
3. Simpler Processor Design

- Plenty of transistors but not enough power
 - Power becomes the ultimate currency in processor design
- Complex logic for performance is power hungry
 - Not easy to eke out the last bit of performance out of a program
 - Diminishing returns on performance for power investment
- Push towards simpler architectures:
 - *Multi-cores*: Run multiple programs (threads) on simple cores
 - *GPUs*: Run each instruction on massively parallel compute units
 - *Caches*: Memory caches are power efficient (low dynamic power)



Memory Wall

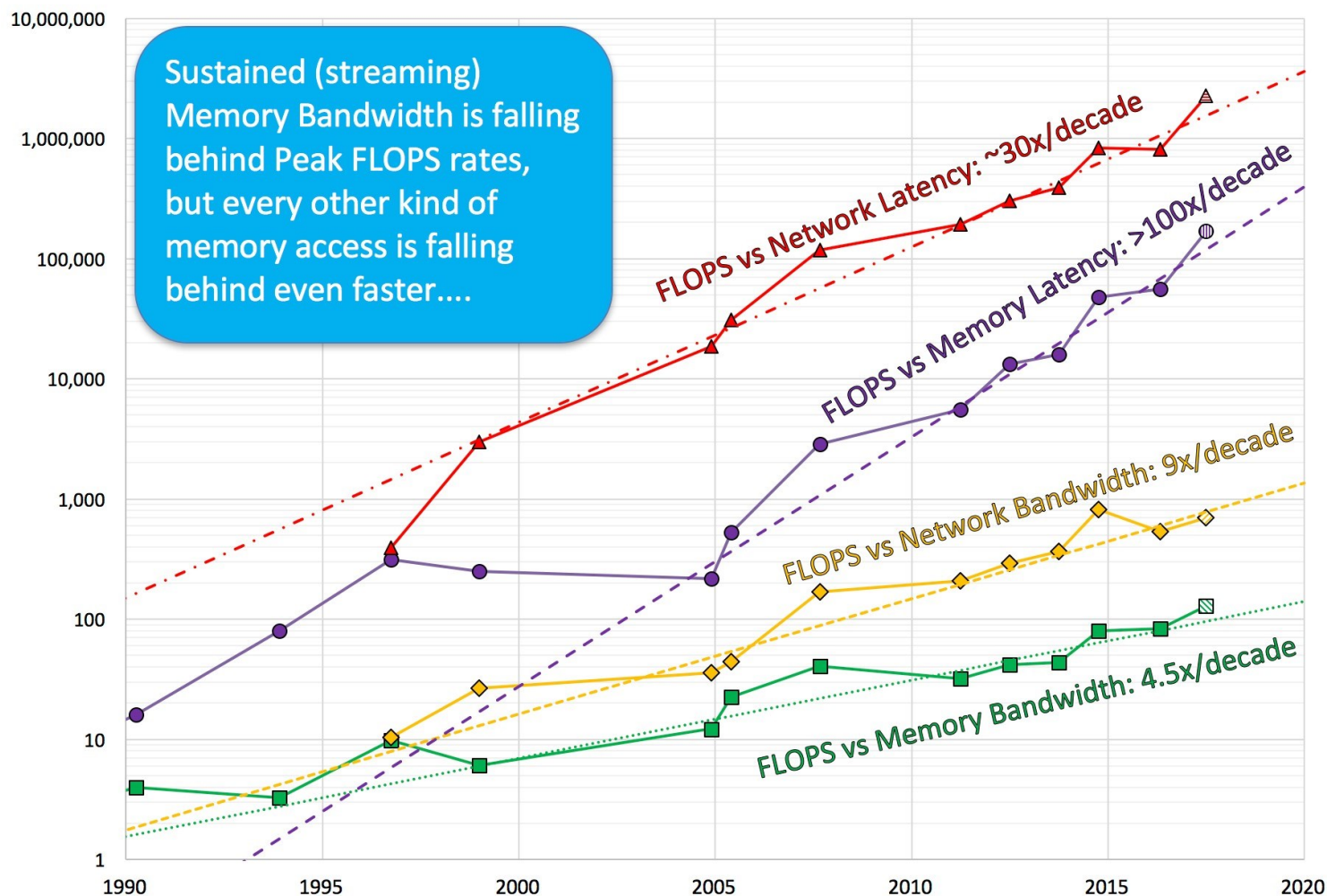
- Refers to both *latency (ns)* and *bandwidth (GB/s)*
 - CPU frequency and overall performance increased dramatically
 - Memory (DRAM) latency and bandwidth have lagged far behind
- Why?
 - Limit on the number of CPU / DRAM pins that can be soldered on



- DRAM manufacturers have traditionally prioritized capacity
- DDR1 (1998): 1.6 GB/s → DDR4 (2014): 25.6 GB/s
(Impressive? Not so much compared to CPU performance)



Memory Wall



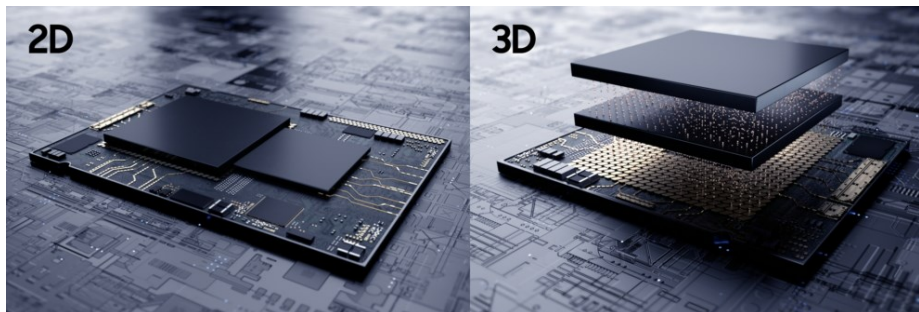
Source: SC16 Invited Talk “Memory Bandwidth and System Balance in HPC Systems” by John D. McCalpin

■ FLOPS = floating point operations per second (performance)



Memory Wall

- Where did the Memory Wall push architecture?
- *Caches*: If hit in cache, no need to go to memory
 - Caching reduces both data access latency/bandwidth
- *3D-Stacked Memory*: Stack CPU on top of memory
 - Drill vias, or holes, through silicon to bond CPU with memory
 - Through silicon vias (TSVs) have low latency / high bandwidth



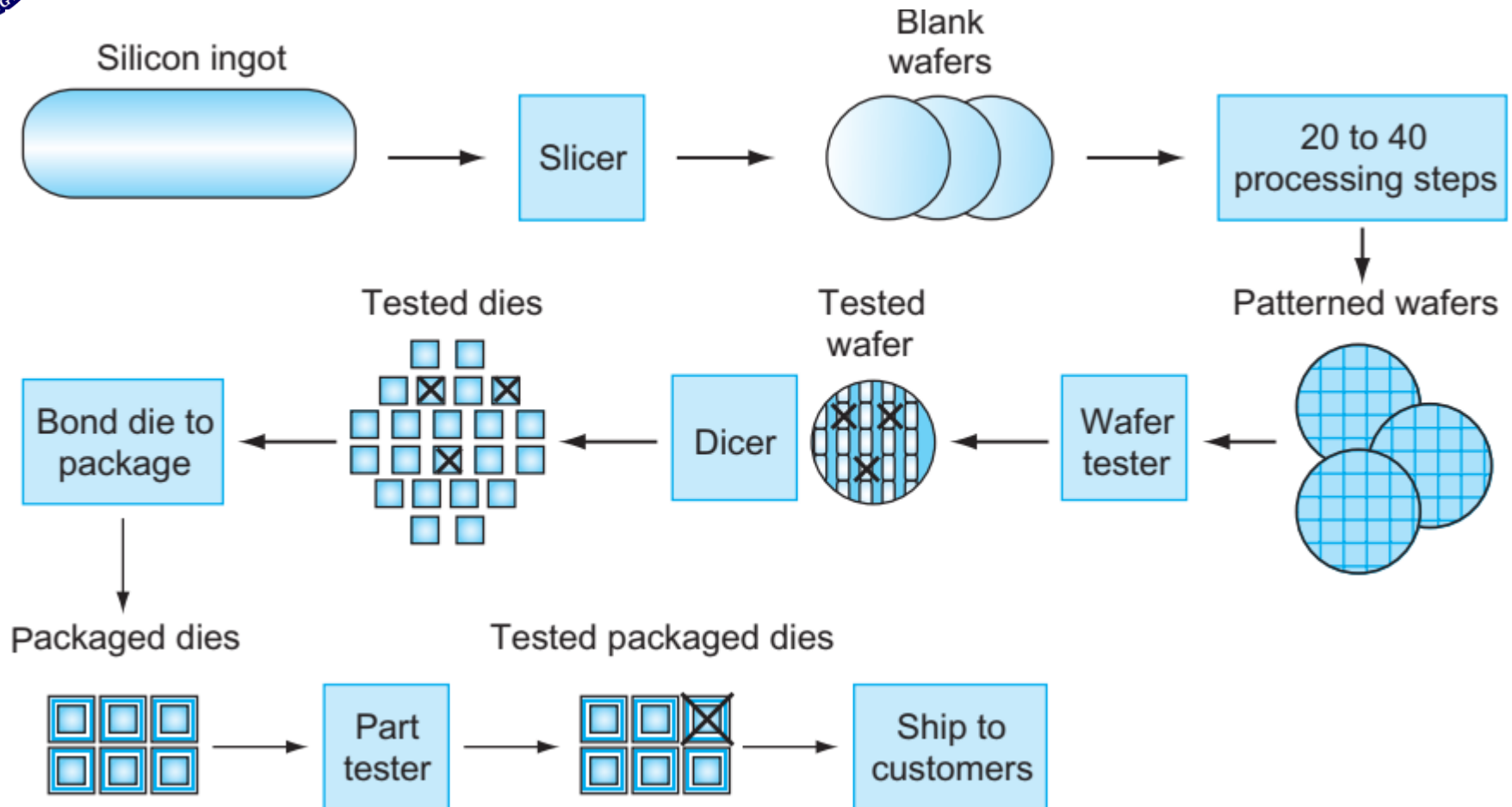


Variability

- *Variability*: differences in speed of individual transistors
 - If fab can't ensure uniformity of transistors, speeds will differ
 - Speed differences mostly come from variations in V_{th} :
 - low V_{th} → cycle time ↓ but leakage power ↑
 - high V_{th} → cycle time ↑ but leakage power ↓
- If unlucky and a logic path has lots of *slow* transistors
 - CPU may miss clock cycle time if path is exercised
 - CPU must be discarded, since it malfunctions
- If unlucky and a region has too many *fast* transistors
 - Region may generate too much heat due to low V_{th}
 - CPU must be discarded, due to overheating
- Leads to low chip *yield*



Wafer Yield



- Lower yield leads to higher production cost



Variability

- Where did Variability push architecture?
- *Product binning*: Sell slower CPUs at a cheaper “bin”
 - And rate slower CPUs at a lower CPU frequency
 - Instead of discarding them as “malfunctioning”
- *Multi-cores*: Easy to disable one or two buggy cores
 - Compared to single core where subcomponents must be disabled
 - When cores are disabled, sold as a cheaper chip
- *Limited pipelining*: pipelining exacerbates variability
 - With long stages, many transistors so tend to even each other out
 - With short stages, few transistors so probable all are slow



Intel i9 Product Binning

Model	# Cores	# Threads	Base Clock	All Core Turbo	Turbo Boost	Total L3 Cache	PL1 TDP
i9-10900K	10	20	3.7	4.8	5.1	20	125
i9-10900KF	10	20	3.7	4.8	5.1	20	125
i9-10900	10	20	2.8	4.5	5.0	20	65
i9-10900F	10	20	2.8	4.5	5.0	20	65
i9-10900T	10	20	1.9	3.7	4.5	20	35
i7-10700K	8	16	3.8	4.7	5.0	16	125
i7-10700KF	8	16	3.8	4.7	5.0	16	125
i7-10700	8	16	2.9	4.6	7.7	16	65
i7-10700F	8	16	2.9	4.6	4.7	16	65
i7-10700T	8	16	2.0	3.7	4.4	16	35
i5-10600K	6	12	4.1	4.5	4.8	12	125
i5-10600KF	6	12	4.1	4.5	4.8	12	125
i5-10600	6	12	3.3	4.4	4.8	12	65
i5-10600T	6	12	2.4	3.7	4.0	12	35
i5-10500	6	12	3.1	4.2	4.5	12	65
i5-10500T	6	12	2.3	3.5	3.8	12	35
i5-10400	6	12	2.9	4.0	4.3	12	65
i5-10400F	6	12	2.9	4.0	4.3	12	65
i5-10400T	6	12	2.0	3.2	3.6	12	35

Why the close to 4X difference?
Clock difference is just 2X!

Produced from one wafer

4 out of 10 cores were discarded.

Source: <https://www.techspot.com/article/2039-chip-binning/>

* TDP is calculated using the Base Clock frequency at a nominal supply voltage



Opportunities for Speed Improvement

- So Dennard Scaling is dead
 - Free CPU frequency gains are no longer there

- And we are walled in by technology constraints
 - Power wall
 - Memory wall
 - Variability
 - ...

- Where do architects go look for performance?



Improving Execution Time

- Execution time = $\frac{\text{instructions}}{\text{program}} \times \frac{\text{cycles}}{\text{instructions}} \times \frac{\text{seconds}}{\text{cycle}}$
- Improving $\frac{\text{seconds}}{\text{cycle}}$:
 - *Pipelining* can lead to higher frequencies
- Improving $\frac{\text{cycles}}{\text{instructions}}$:
 - *Caching* can reduce cycles for memory instructions
 - *Superscalars* can execute multiple instructions per cycle
 - *Multi-cores* execute multi-instructions from multi-threads
- Improving $\frac{\text{instructions}}{\text{program}}$:
 - *GPUs* are *SIMD (Single Instruction Multiple Data)* processors



What about Other Performance Goals?

- We talked a lot about execution speed
- But there are other performance goals such as:
 - Energy efficiency
 - Reliability
 - Security
 - ...
- In this class, we will mainly focus on speed
 - Not that other goals are not important
 - We will touch upon other goals when relevant
 - Performance will be used synonymously with speed



Textbook Chapters

- Please review Chapter 1 of the textbook.